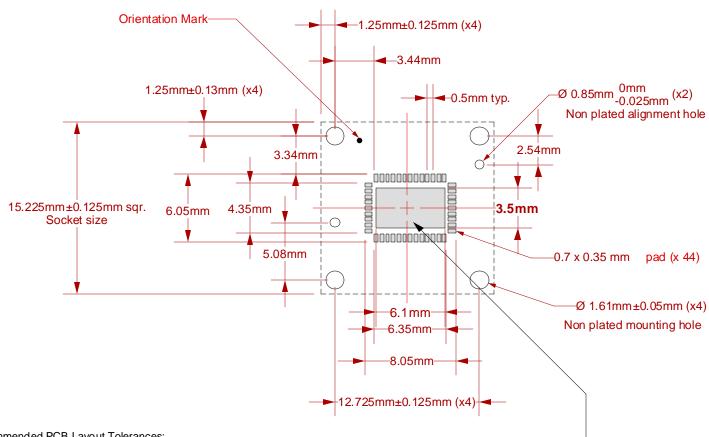


SG-MLF-7013 Drawing	Status: Released	Scale:	-	Rev: D
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All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

*Note: MLF pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.



Recommended PCB Layout Tolerances: ±0.025mm unless stated otherwise.

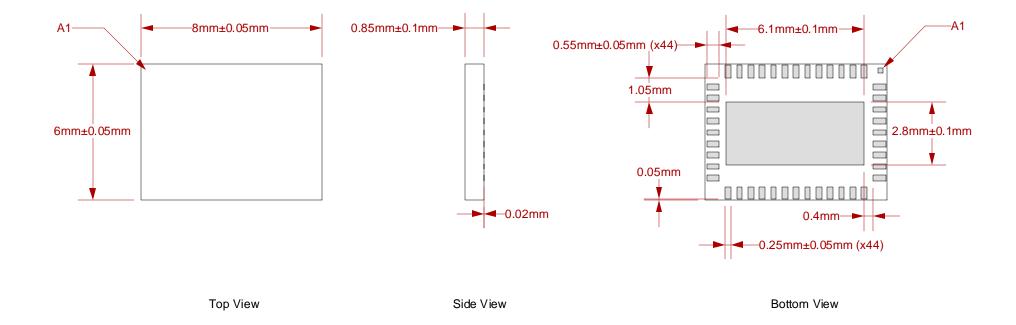
Target PCB Recommendations
Total thickness: 1.6mm min.
Plating: Gold or Solder finish

PCB Pad height: Same or higher than solder mask

**** To effectively conduct heat away from the package a thermal pad is recommended with vias spaced 1.0 to 1.2 mm pitch and a diameter of 0.3 to 0.33 mm. Ideally 1 via for every 3 leads has been shown to work well.

NOTE: Steel backing plate may be required based on end user's application

SG-MLF-7013 D	rawing	Status: Released	Scale: 3:1		Rev: D
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		File: SG-MLF-7013 Dwg		Modified: 11/11/14	



All dimensions are in mm.

SG-MLF-7013 Drawing		Status: Released	Scale: 3:1		Rev: D
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		File: SG-MLF-7013 Dwg		Modified: 11/11/14	